

#### 1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C unless otherwise specified)

Symbol	Paran	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage	T <sub>j</sub> = -40 °C to + 175 °C	650	V
I <sub>F(RMS)</sub>	Forward rms current			Α
I <sub>F(AV)</sub>	Average forward current	T <sub>c</sub> = 145 °C <sup>(1)</sup> , DC	6	Α
I <sub>FSM</sub>	Surge non repetitive forward current	$t_p$ = 10 ms sinusoidal, $T_c$ = 25 °C	60	
		$t_p$ = 10 ms sinusoidal, $T_c$ = 125 °C	52	Α
		$t_p$ = 10 µs square, $T_c$ = 25 °C	400	
I <sub>FRM</sub>	Repetitive peak forward current	$T_c$ = 145 °C <sup>(1)</sup> , $T_j$ = 175 °C, $\delta$ = 0.1	23	Α
T <sub>stg</sub>	Storage temperature range	-55 to +175	°C	
Tj	Operating junction temperature range <sup>(2)</sup>			°C

<sup>1.</sup> Value based on  $R_{th(j-c)}$  max.

**Table 2. Thermal parameters** 

Symbol	Parameter	Typ. value	Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	1.6	2.4	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$	-	5	60	μA
		T <sub>j</sub> = 150 °C		-	50	250	
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 6 A	-	1.45	1.65	V
VF <sup>(-)</sup>		T <sub>j</sub> = 150 °C		-	1.7	2.05	

<sup>1.</sup>  $t_p = 10 \text{ ms}, \ \delta < 2\%$ 

To evaluate the conduction losses, use the following equation:

$$P = 0.972 \times I_{F(AV)} + 0.180 \times I_{F^{2}(RMS)}$$

Table 4. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Тур.	Unit
Q <sub>cj</sub> <sup>(1)</sup>	Total capacitive charge	V <sub>R</sub> = 400 V	18	nC
C <sub>j</sub>	Total capacitance	V <sub>R</sub> = 0 V, T <sub>c</sub> = 25 °C, F = 1 MHz	300	pF
		$V_R = 400 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ MHz}$	30	þr

<sup>1.</sup> Most accurate value for the capacitive charge:  $Q_{cj}=\int_0^{V_{OUT}} c_j (V_R) \times d_{VR}$ 

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<sup>2.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

<sup>2.</sup>  $t_p = 500 \ \mu s, \ \delta < 2\%$ 



#### 1.1 Characteristics (curves)

Figure 1. Forward voltage drop versus forward current (typical values, low level)

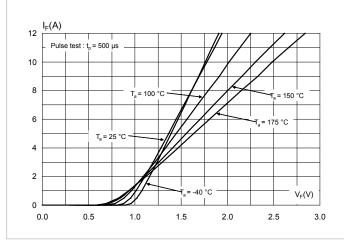


Figure 2. Forward voltage drop versus forward current (typical values, high level)

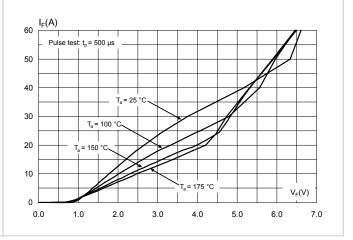


Figure 3. Reverse leakage current versus reverse voltage applied (typical values)

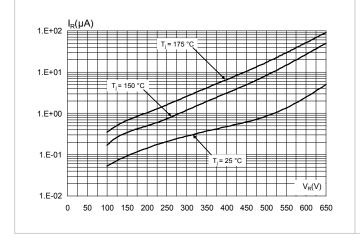


Figure 4. Peak forward current versus case temperature

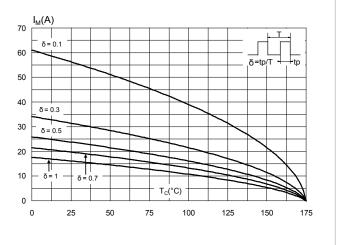


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

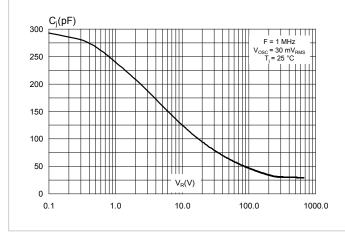
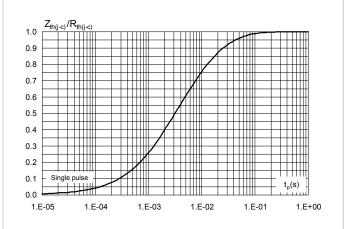


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 7. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

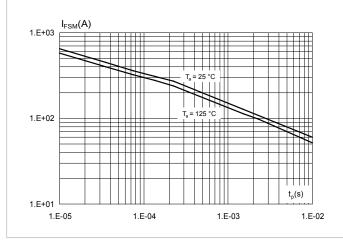
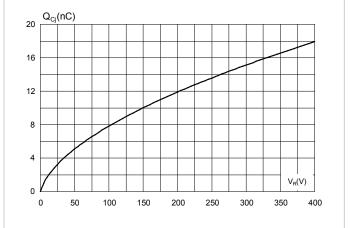


Figure 8. Total capacitive charges versus reverse voltage applied (typical values)



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## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

### 2.1 DPAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

Beating plane

Seating plane

A2

(L1)

V2

0.25

Gauge plane

Figure 9. DPAK package outline

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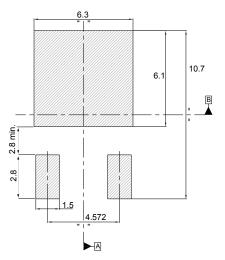
Downloaded from Arrow.com.



Table 5. DPAK mechanical data

	Dimensions						
Dim.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	2.20		2.40	0.087		0.094	
A1	0.90		1.10	0.035		0.043	
A2	0.03		0.23	0.001		0.009	
b	0.64		0.90	0.025		0.035	
b4	5.20		5.40	0.205		0.213	
С	0.45		0.60	0.018		0.024	
c2	0.48		0.60	0.019		0.024	
D	6.00		6.20	0.236		0.244	
D1	4.95	5.10	5.25	0.195	0.201	0.207	
E	6.40		6.60	0.252		0.260	
E1	4.60	4.70	4.80	0.181	0.185	0.189	
е	2.16	2.28	2.40	0.085	0.090	0.094	
e1	4.40		4.60	0.173		0.181	
Н	9.35		10.10	0.368		0.398	
L	1.00		1.50	0.039		0.059	
(L1)	2.60	2.80	3.00	0.102	0.110	0.118	
L2	0.65	0.80	0.95	0.026	0.031	0.037	
L4	0.60		1.00	0.024		0.039	
R		0.20			0.008		
V2	0°		8°	0°		8°	

Figure 10. DPAK recommended footprint (dimensions are in mm)



The device must be positioned within �005 AB

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# 3 Ordering Information

**Table 6. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPSC6H065BY-TR	PSC6H 065Y	DPAK	0.32 g	2500	Tape and reel

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## **Revision history**

**Table 7. Document revision history** 

Date	Version	Changes
13-Mar-2018	1	Initial release.

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